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| Objective |
| Batch name: |
| This is an example process flow to be used as a template. It should contain   * The objective of the process * Substrates/samples used in the flow. Both actual samples to be processed (device wafers) and monitor samples for the different process steps * The Process flow main processes and steps * Recommended: Figures illustrating the sample before and after each main process step.   How to use this template:   * Fill out the fields in the heading! * Add process steps by using Quick Parts under Insert (your cursor should be located below the “Comments:”-line of the previous step).  Select the “Process Flow” item. * Also other document parts can be inserted the same way: Substrate Info, Figure Table and TOC. |

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| Substrates | | | | | | | | | |
| Substrate | Orient. | Size | Doping/type | Polish | thickness | Box | Purpose | # | Sample ID |
| Silicon | <100> | 4” | n (Phos.) | DSP | 350±30µm |  | Device wafers |  |  |
| Silicon | <100> | 4” | n (Phos.) | DSP | 350±30µm |  | Dummy wafer |  |  |

Comments: wafer bow on S1-S10 should be <2µm

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| 1. Preparation | | | | | |
| Step Heading | Equipment | Procedure | Recipe/mask | Target±tol. | Comments |
| * 1. Wafer selection | Wafer box | Take the wafers from the storage and put them in a wafer box.  Take the monitors from the box and put them in a sample tray. |  |  | Note the wafer IDs in the batch traveler |
| * 1. Cleaning | 7-Up | Clean all wafers and monitors |  |  |  |
| * 1. Inspection | lamp | Optical inspect wafers |  |  | Take new wafers if they cannot be well cleaned |
| * 1. Start bake-out | 250°C oven | Place steel carrier with the wafers and monitors in the oven | Bake250 | >1 hour | 1 hour baking |

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| 1. Lithography | | | | | | | |
| Step Heading | Equipment | | Procedure | Recipe/mask | Target±tol. | | Comments |
| * 1. Surface treatment | | HMDS oven | Load all wafers in oven for xx mins | Recipe 4 | >xx mins | Note time in traveler | |
| * 1. Clean spinner | | Track 1 | Clean spinner nozzle and run the dummy wafer |  |  |  | |
| * 1. Coat wafers | | Track 1 | Coat the sharp wafers  AZ5214e Novolac resist  Softbake on hotplate, 90°C, 60 sec | Recipe: PR1\_5 | 1.5µm± 0.2µm | Resist thickness not checked | |
| * 1. Exposure | | KS aligner | Align to flat.  Expose for xx sec | Mask: lines1 |  |  | |
| * 1. Develop | | Wet bench | Develop in YYYY for 120 sec |  | 120±10s | Note time in traveler | |
| * 1. Rinse | | Wet bench | Rinse in DI water for 5 min |  | 300±30s |  | |

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| Figures | | |
| Figure Caption | Figure | Step reference |
| 1. After development |  | 2 Lithography |

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